

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	9500	(257/98,99,100,676).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:44
L2	1056	L1 and (("light emitting device" "light emitting diode") near3 (chip die))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:44
L3	950	L2 and (substrate base "mounting plate" "support plate" body plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:45
L4	679	L3 and (encapsulate encapsulating encapsulation encapsulant seal sealant resin encase encasing encased)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:48
L5	78	L4 and @ad< "20001228"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:49
L6	75	L5 and (connect connection interconnection wire wiring lead trace conductor "lead frame" metalization)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 10:50
L7	6721	((("light emitting device" "light emitting diode") near3 (chip die))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:08
L8	5162	L7 and (substrate base "mounting plate" "support plate" body plate tab)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:09
L9	2705	L8 and (encapsulate encapsulating encapsulation encapsulant seal sealant resin encase encasing encased)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:09
L10	2288	L9 and (connect connection interconnection wire wiring lead trace conductor "lead frame" metalization)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:09
L11	337	L10 and @ad< "20001228"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:10
L12	125	L11 and (substrate base "mounting plate" "support plate" body plate tab) near5 (encapsulate encapsulating encapsulation encapsulant seal sealant resin encase encasing encased)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/12/01 11:11

12/ 1/ 2008 11:56:40 AM

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